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Part Number: [73780-1126](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 16.00mm, Pin Length 2.00mm, Solder Tail

Documents:

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

UL E29179

General

Product Family Backplane Connectors
Series [73780](#)
Application Daughtercard, Mezzanine
Comments Solder Tail
Component Type PCB Receptacle
Overview [HDM® Backplane Connector System](#)
Product Name HDM®
Style N/A
UPC 800754870535

Physical

Circuits (Loaded) 144
Circuits (maximum) 144
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Copper-Nickel-Tin
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 20.030/g
Number of Columns 24
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 2.00mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 1.60mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C
Termination Interface: Style Through Hole

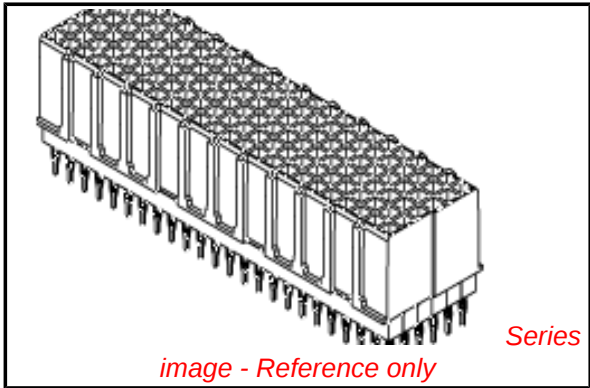


image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Low-Halogen Status
Low-Halogen

China RoHS



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environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73780Series](#)

Mates With

HDM® Board-to-Board Backplane Header
[73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) ,
[73944](#) , [74349](#) , [74428](#). HDM® Board-to-
Board Stacking Header [73769](#) , [73770](#) ,
[73782](#) , [73783](#) , [73771](#)

Electrical

Current - Maximum per Contact	15A, 1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999
Sales Drawing	SD-73780-004

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